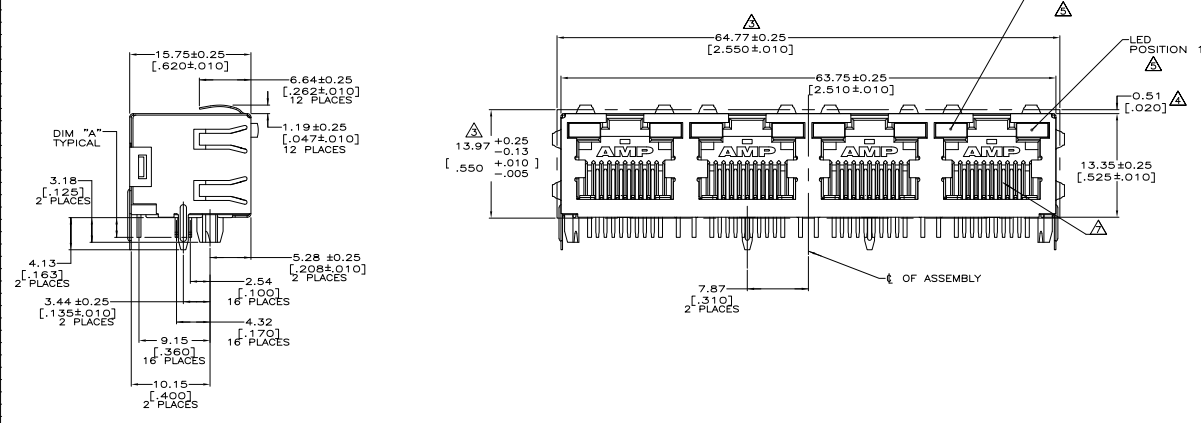
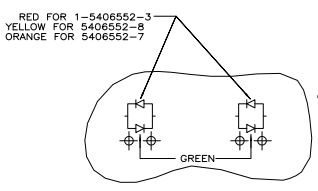


THIS DRAWING IS UNPUBLISHED  
 UNLESS INDICATED OTHERWISE  
 ALL RIGHTS RESERVED

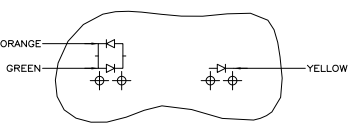
REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00	REVISED PER EDD-11-005033			



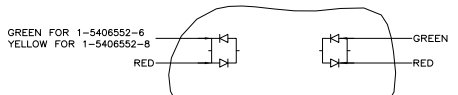
- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[0.14] THICK PHOS BRONZE PLATED WITH 3.81µm[0.00150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA, ENTIRE TERMINAL PLATED WITH 1.27µm [0.00050] MINIMUM THICK NICKEL.  
 SHIELD - 0.19[0.007] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.00050] MINIMUM SATIN NICKEL WITH 2.03µm[0.00080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[0.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm THICK Sn/Cu OVER 2.03 µm THICK Ag OVER 1.02 µm THICK Cu OVER 3.56 µm THICK Ni OVER 1.02 µm THICK Cu UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.



BI-COLOR LED CURRENT DIAGRAM



LED CURRENT DIAGRAM  
 5406552-9 ONLY



BICOLOR LED CURRENT DIAGRAM

	.100	RED/YELLOW	RED/GREEN	1-5406552-8
	.100	GREEN		1-5406552-7
	.126	RED/GREEN	RED/GREEN	1-5406552-6
	.100	SEE VIEW A (SHEET 2)	SEE VIEW A (SHEET 2)	1-5406552-5
	.100	RED	GREEN	1-5406552-4
	.100	GREEN/RED	GREEN/RED	1-5406552-3
	.120	YELLOW	GREEN	1-5406552-1
	.100	GREEN/ORANGE	YELLOW	5406552-9
	.100	GREEN/YELLOW	GREEN/YELLOW	5406552-8
	.100	GREEN/ORANGE	GREEN/ORANGE	5406552-7
OBSOLETE	.100	YELLOW	YELLOW	5406552-6
	.100	GREEN	GREEN	5406552-5
	.100	GREEN	YELLOW	5406552-4
OBSOLETE	.100	YELLOW		5406552-3
	.100		GREEN	5406552-2
	.100	YELLOW	GREEN	5406552-1
		POSITION 2	POSITION 1	PART NUMBER
		DIM A		
		SOLDER TAIL LENGTH		

THIS DRAWING IS A CONTROLLED DOCUMENT. **TE Connectivity**

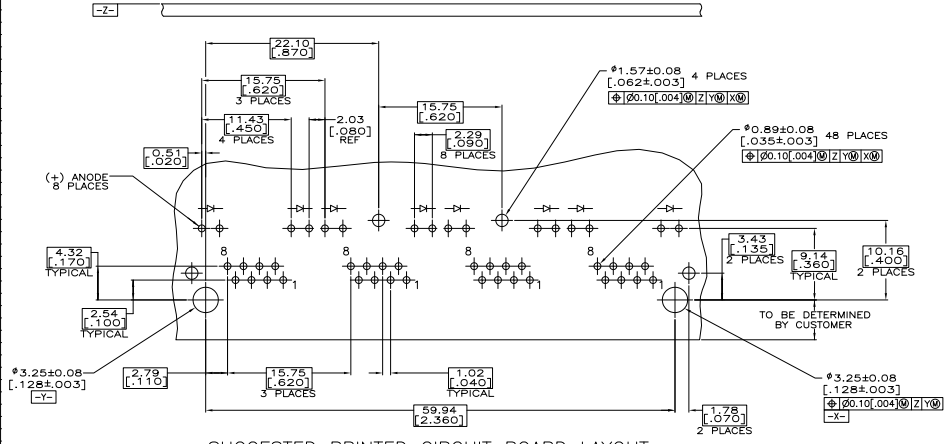
DATE: 108-1163-4  
 REV: 114-2154  
 PART: 100779

INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL GROUND, WITH LED

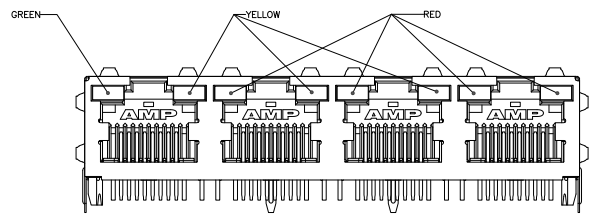
CUSTOMER DRAWING

THIS DRAWING IS UNPUBLISHED  
 ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	APP'D
AA	00	SEE SHEET 1	-	-



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)



THIS DRAWING IS A CONTROLLED DOCUMENT.		11 SPINELLI (A. MANFROTTO) 12 WESTMAN (MANFROTTO)	<b>TE Connectivity</b> INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL MOUNTING, WITH LED
DIMENSIONS: mm UNLESS OTHERWISE SPECIFIED DEC: ±.005 (0.15) FRA: ±.002 (0.05) DIA: ±.001 (0.025)	108-1163-4 REV: 114-2154	DATE: 11-11-14 DRAWING NO: 100779 CUSTOMER DRAWING: G=5406552	SHEET: 4.1 OF: 2 OF: 2 DR